

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S):

Fitzgerald et al.

SERIAL NO.:

10/625,018

**GROUP NO.:** 

Not Yet Assigned

FILING DATE:

July 23, 2003

**EXAMINER:** 

Not Yet Assigned

TITLE:

CMOS Inverter and Integrated Circuits Utilizing Strained Silicon

Surface Channel MOSFETs

# CERTIFICATE OF FIRST CLASS MAILING UNDER 37 C.F.R. 1.8

I hereby certify that this correspondence, and any document(s) referred to as enclosed herein, is/are being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 27 day of December, 2003.

Emy Walsh

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

#### Submitted herewith are:

- 1. Transmittal Form (1 pg.);
- 2. Supplemental Information Disclosure Statement (2 pgs.);
- 3. Form PTO-1449 (13 pgs.);
- 4. Copies of cited references B1-B38 and C1-C91; and
- 5. Return Receipt Postcard.

/	10 1 15 16 1		Application S	Serial Number	5,018	
/		Filing Date		July 2.	3, 2003	
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	FORM		Attorney Doc	ket No.	ASC-0	043C2
			Patent No.		Not A	applicable
			Issue Date		Not A	Applicable
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Fee	Transmittal Form		Copy of Notice	to File Missing		Notice of Appeal to Board
			Parts of Applica			of Patent Appeals and Interferences
! 	☐ Check Attached ☐ Copy of Fee Transmittal Form		Formal Drawin	g(s)		Appeal Brief (in triplicate)
	Amendment/Response		Request For Co			Status Inquiry
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			Terminal Disclaimer			Certificate of Facsimile Transmission under 37 C.F.R. 1.8
	Petition for Extension of Time			aration and Power r Utility or Design ttion		Additional Enclosure(s) (please identify below)
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5	Form PTO-1449  Copies of IDS Citations (B1-B38 and C1-C91)		CD(s) for large table or computer program			
	Certified Copy of Priority Document(s)		Amendment A	fter Allowance		
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Direct a	All correspondence to: Patent Ad Testa, Hu High Stre 125 High Boston, M Tel. No.: Fax No.:	hibeault, LLP	Date: December 27 Reg. No. 50,773 Tel. No.: (617) 248 Fax No.: (617) 248	- 3-7453	Respectfully submitted,  Mark L. Belotorodov Attorney for Applicants Testa, Hurwitz & Thibeault, LLP High Street Tower 125 High Street Boston, MA 02110	



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# SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicants hereby make of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. In accordance with the U.S. Patent Office's partial waiver of the requirement under 37 C.F.R. 1.98 (a)(2)(i), only copies of the foreign patent documents and non-patent publications are enclosed.

It is respectfully requested that each of the patents and publications listed on the attached Form PTO-1449, and other information contained herein, be made of record in this application.

In addition, Applicants wish to inform the Examiner about the following commonlyowned, co-pending patent applications, including all cited references and Office actions issued therein:

U.S. Serial Number	Filing Date	Inventor Name
09/599,260	06/22/2000	Wu et al.
09/764,177	01/17/2001	Fitzgerald
09/906,545	07/16/2001	Fitzgerald
10/216,085	08/09/2002	Fitzgerald
10/264,935	10/04/2002	Lochtefeld et al.

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In accordance with the provisions of 37 C.F.R. 1.97, this statement is being filed before the mailing of the first Office action on the merits. Applicants believe no fees are due for this paper to be entered and considered, but the Commissioner is hereby authorized to charge Deposit Account No. 20-0531 for any required fees that may be due.

Date: December <u>27</u>, 2003 Reg. No. 50,773

Tel. No.: (617) 248-7453 Fax No.: (617) 248-7100

2729959

Respectfully submitted,

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INFORMATION DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.: ASC-043C2

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	A6	5,155,571	10/13/1992	Wang et al.			
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	A19	5,310,451	05/10/1994	Tejwani et al.			
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	A45	5,714,777	02/03/1998	Ismail et al.			-
<del> </del>	A46	5,728,623	03/17/1998	Mori			
	A47	5,739,567	04/14/1998	Wong			
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	BI	41 01 167	07/23/1992	DE				N	Abstract
	B2 /	0 514 018	11/19/1992	EP				N	Y
	B3/	0 587 520	03/16/1994	EP				N	Y

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#### FOREIGN PATENT DOCUMENTS DOCUMENT DATE COUNTRY FILING ENGLISH EXAM. **CLASS** SUB **ABSTRACT** INIT. NUMBER CODE **CLASS** DATE ONLY LANG (Y/N) B4 / 0 683 522 11/22/1995 EP Y Ν B5 0 828 296 03/11/1998 EP Ν Y B6 \_ 0 829 908 03/18/1998 EP N Y B7 0 838 858 04/29/1998 EP N Abstract B8 1 020 900 07/19/2000 EP Ν Y B9 1 174 928 01/23/2002 EP N Y B10 2 342 777 04/19/2000 GB Y B11 5-166724 07/02/1993 JР N Abstract B12 6-177046 06/24/1994 ЛР N Abstract Y B13 6-252046 09/09/1994 JP Y B14 7-94420. 04/07/1995 JP Ν N B15 7-240372 09/12/1995 JР N Abstract B16 10-270685 10/09/1998 JP Y N JР B17 2000-021783 01/21/2000 N Y B18 2000-031491 01/28/2000 JР Ν Y Y B19 2001-319935 11/16/2001 JP N 2002-076334 03/15/2002 JР Y B20, Ν B21 2002-164520 06/07/2002 JP Ν Y B22 2002-289533 10/04/2002 JP Ν Y 98/59365 WO Y B23 12/30/1998 Ν B24 99/53539 10/21/1999 WO N Y 00/48239 WO Y B25 08/17/2000 N B26 00/54338 09/14/2000 WO Y WO Y B27 01/022482 03/29/2001 N WO B28 01/54202 07/26/2001 N Y B29 01/93338 12/06/2001 WO Y N **EXAMINER** DATE CONSIDERED



**FORM PTO - 1449** 

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ATTORNEY DOCKET NO.: ASC-043C2

APPLICANT(S): Fitzgerald et al.

SERIAL NO.: 10/625,018

	•	FILING DATE: July 23, 2003 GROUP: Not yet assigned				
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ATTORNEY DOCKET NO.: ASC-043C2

APPLICANT(S): Fitzgerald et al.

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		SERIAL NO.: 10/625,018				
		FILING DATE: July 23, 2003 GROUP: Not yet assigned				
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SERIAL NO.: 10/625,018

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**EXAMINER**